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Details	
Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	704
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb7k4f40i3n

Arria V GX, GT, SX, and ST Device Datasheet

1

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This datasheet describes the electrical characteristics, switching characteristics, configuration specifications, and I/O timing for Arria® V devices.

Arria V devices are offered in commercial and industrial grades. Commercial devices are offered in –C4 (fastest), –C5, and –C6 speed grades. Industrial grade devices are offered in the –I3 and –I5 speed grades.

Related Information

Arria V Device Overview
Provides more information about the densities and packages of devices in the Arria V family.

Electrical Characteristics

The following sections describe the operating conditions and power consumption of Arria V devices.

Operating Conditions

Arria V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Arria V devices, you must consider the operating requirements described in this section.

Absolute Maximum Ratings

This section defines the maximum operating conditions for Arria V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Minimum differential eye opening at the receiver serial input pins[30]	—	100	—	—	100	—	—	mV
V_{ICM} (AC coupled)	—	—	0.7/0.75/ 0.8[31]	—	—	0.7/0.75/ 0.8 [31]	—	mV
V_{ICM} (DC coupled)	≤ 3.2Gbps[32]	670	700	730	670	700	730	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	Ω
t_{LTR}[33]	—	—	—	10	—	—	10	µs
t_{LTD}[34]	—	4	—	—	4	—	—	µs
t_{LTD_manual}[35]	—	4	—	—	4	—	—	µs
$t_{LTR\_LTD\_manual}$[36]	—	15	—	—	15	—	—	µs
Programmable ppm detector[37]	—	±62.5, 100, 125, 200, 250, 300, 500, and 1000						ppm

(30) The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(31) The AC coupled V_{ICM} = 700 mV for Arria V GX and SX in PCIe mode only. The AC coupled V_{ICM} = 750 mV for Arria V GT and ST in PCIe mode only.

(32) For standard protocol compliance, use AC coupling.

(33) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

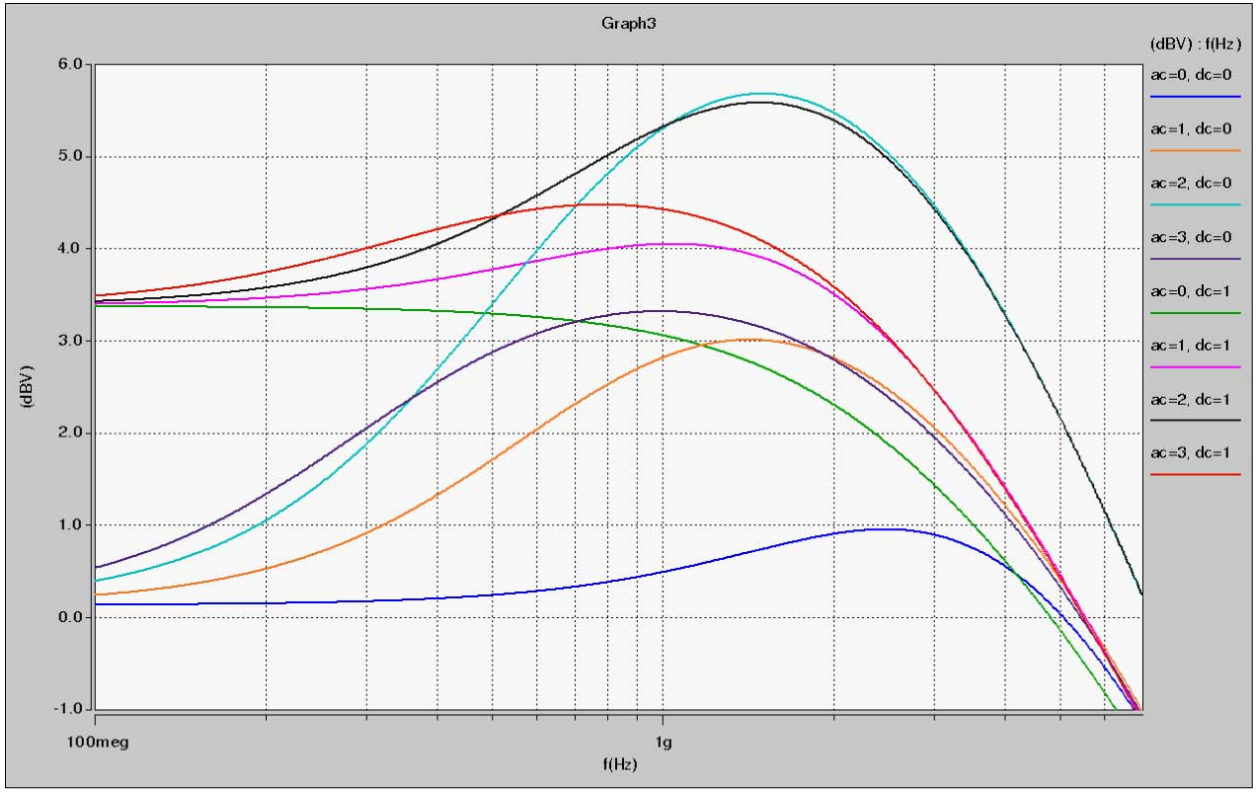
(34) t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.

(35) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.

(36) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain

Figure 1-3: CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices



Protocol	Sub-protocol	Data Rate (Mbps)
Common Public Radio Interface (CPRI)	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4
	CPRI E12LV	1,228.8
	CPRI E12HV	1,228.8
	CPRI E12LVII	1,228.8
	CPRI E24LV	2,457.6
	CPRI E24LVII	2,457.6
	CPRI E30LV	3,072
	CPRI E30LVII	3,072
	CPRI E48LVII	4,915.2
	CPRI E60LVII	6,144
	CPRI E96LVIII(60)	9,830.4
Gbps Ethernet (GbE)	GbE 1250	1,250
OBSAI	OBSAI 768	768
	OBSAI 1536	1,536
	OBSAI 3072	3,072
	OBSAI 6144	6,144
Serial digital interface (SDI)	SDI 270 SD	270
	SDI 1485 HD	1,485
	SDI 2970 3G	2,970

(60) You can achieve compliance with TX channel restriction of one HSSI channel per six-channel transceiver bank.

DSP Block Performance Specifications

Table 1-37: DSP Block Performance Specifications for Arria V Devices

Mode		Performance			Unit
		–I3, –C4	–I5, –C5	–C6	
Modes using One DSP Block	Independent 9 × 9 multiplication	370	310	220	MHz
	Independent 18 × 19 multiplication	370	310	220	MHz
	Independent 18 × 25 multiplication	370	310	220	MHz
	Independent 20 × 24 multiplication	370	310	220	MHz
	Independent 27 × 27 multiplication	310	250	200	MHz
	Two 18 × 19 multiplier adder mode	370	310	220	MHz
	18 × 18 multiplier added summed with 36-bit input	370	310	220	MHz
Modes using Two DSP Blocks	Complex 18 × 19 multiplication	370	310	220	MHz

Memory Block Performance Specifications

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL and set to 50% output duty cycle. Use the Quartus Prime software to report timing for the memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in f_{MAX}.

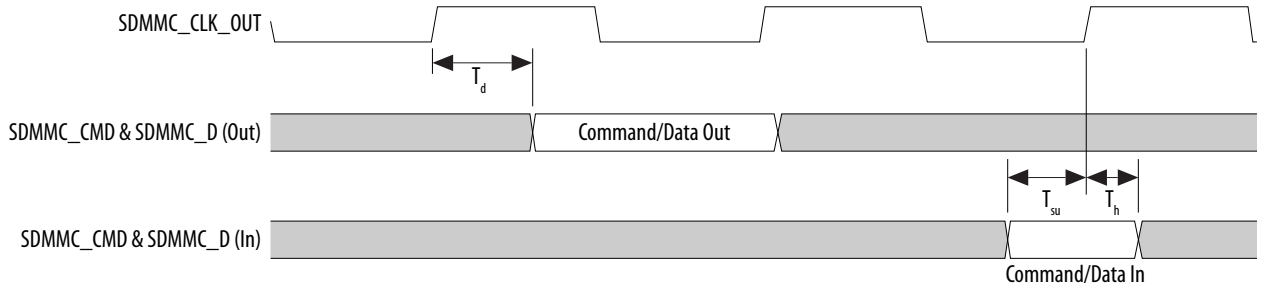
Symbol	Condition	–I3, –C4			–I5, –C5			–C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{x\ Jitter}$ -Emulated Differential I/O Standards with Three External Output Resistor Network	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	260	—	—	300	—	—	350	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.16	—	—	0.18	—	—	0.21	UI
$t_{x\ Jitter}$ -Emulated Differential I/O Standards with One External Output Resistor Network	—	—	—	0.15	—	—	0.15	—	—	0.15	UI
t_{DUTY}	TX output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	%
t_{RISE} and t_{FALL}	True Differential I/O Standards[82]	—	—	160	—	—	180	—	—	200	ps
	Emulated Differential I/O Standards with Three External Output Resistor Network	—	—	250	—	—	250	—	—	300	ps
	Emulated Differential I/O Standards with One External Output Resistor Network	—	—	500	—	—	500	—	—	500	ps

(82) This applies to default pre-emphasis and V_{OD} settings only.

Symbol		Condition	–I3, –C4			–I5, –C5			–C6			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	TCCS	True Differential I/O Standards	—	—	150	—	—	150	—	—	150	ps
		Emulated Differential I/O Standards	—	—	300	—	—	300	—	—	300	ps
Receiver	True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J =3 to 10(76)	150	—	1250	150	—	1250	150	—	1050	Mbps
		SERDES factor J ≥ 8 with DPA(76)(78)	150	—	1600	150	—	1500	150	—	1250	Mbps
	f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(77)	—	(83)	(77)	—	(83)	(77)	—	(83)	Mbps
		SERDES factor J = 1 to 2, uses DDR registers	(77)	—	(79)	(77)	—	(79)	(77)	—	(79)	Mbps
DPA Mode	DPA run length	—	—	—	10000	—	—	10000	—	—	10000	UI
Soft-CDR Mode	Soft-CDR ppm tolerance	—	—	—	300	—	—	300	—	—	300	±ppm
Non-DPA Mode	Sampling Window	—	—	—	300	—	—	300	—	—	300	ps

(83) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

Figure 1-11: SD/MMC Timing Diagram



Related Information

Booting and Configuration Chapter, Arria V Hard Processor System Technical Reference Manual
Provides more information about CSEL pin settings in the SD/MMC Controller CSEL Pin Settings table.

USB Timing Characteristics

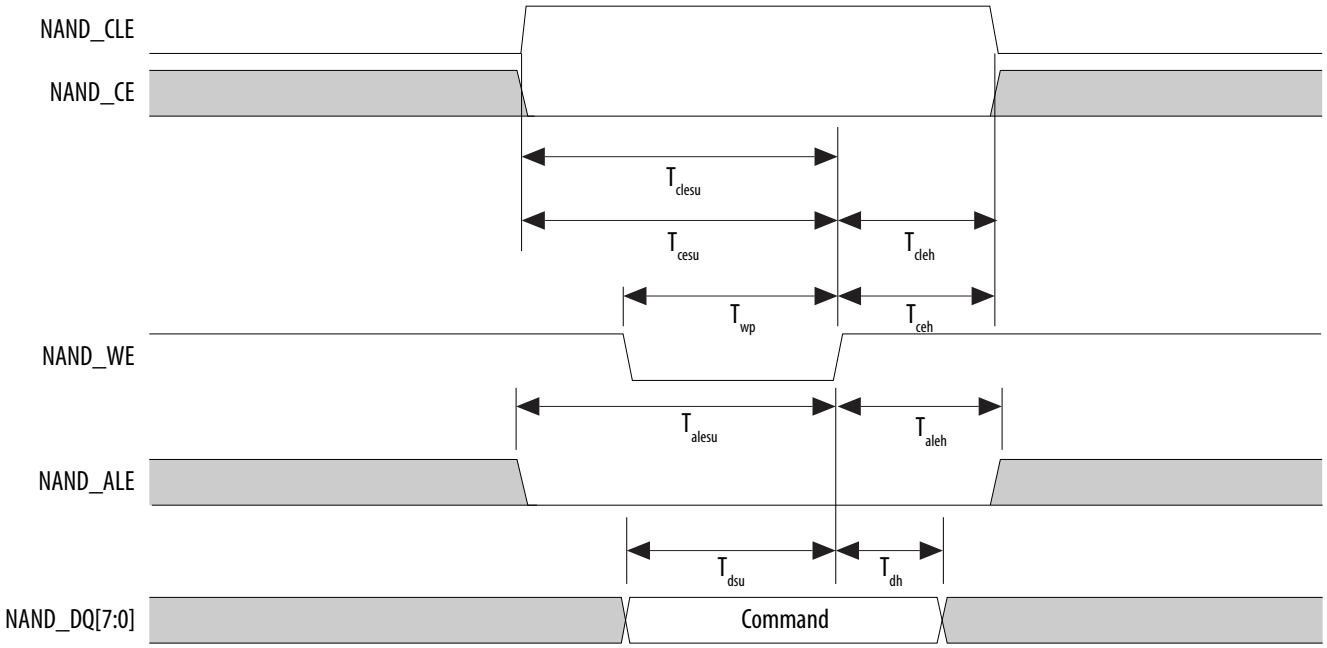
PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.

Table 1-55: USB Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	USB CLK clock period	—	16.67	—	ns
T_d	CLK to USB_STP/USB_DATA[7:0] output delay	4.4	—	11	ns
T_{su}	Setup time for USB_DIR/USB_NXT/USB_DATA[7:0]	2	—	—	ns
T_h	Hold time for USB_DIR/USB_NXT/USB_DATA[7:0]	1	—	—	ns

Symbol	Description	Min	Max	Unit
T_{dh} (89)	Data to write enable hold time	5	—	ns
T_{cea}	Chip enable to data access time	—	25	ns
T_{rea}	Read enable to data access time	—	16	ns
T_{rhz}	Read enable to data high impedance	—	100	ns
T_{rr}	Ready to read enable low	20	—	ns

Figure 1-17: NAND Command Latch Timing Diagram



Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

FPP Configuration Timing
Provides the FPP configuration timing waveforms.

AS Configuration Timing

Table 1-68: AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices

The minimum and maximum numbers apply to both the internal oscillator and CLKUSR when either one is used as the clock source for device configuration.

The t_{CF2CD}, t_{CF2ST0}, t_{CFG}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for passive serial (PS) mode listed in PS Timing Parameters for Arria V Devices table. You can obtain the t_{CF2ST1} value if you do not delay configuration by externally holding nSTATUS low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to the AS_DATA0/ASDO output	—	2	ns
t_{SU}	Data setup time before the falling edge on DCLK	1.5	—	ns
t_{DH}	Data hold time after the falling edge on DCLK	0	—	ns
t_{CD2UM}	CONF_DONE high to user mode	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

- **PS Configuration Timing** on page 1-81
- **AS Configuration Timing**
  Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1506(103)	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506(104)	µs

(103) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(104) You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

The Quartus Prime Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

Arria V I/O Timing Spreadsheet
Provides the Arria V Excel-based I/O timing spreadsheet.

Programmable IOE Delay

Table 1-76: I/O element (IOE) Programmable Delay for Arria V Devices

Parameter[112]	Available Settings	Minimum Offset[113]	Fast Model		Slow Model					Unit
			Industrial	Commercial	–C4	–C5	–C6	–I3	–I5	
D1	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns
D3	8	0	1.763	1.795	2.999	3.496	3.571	3.031	3.643	ns
D4	32	0	0.508	0.518	0.869	1.063	1.063	1.063	1.057	ns
D5	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns

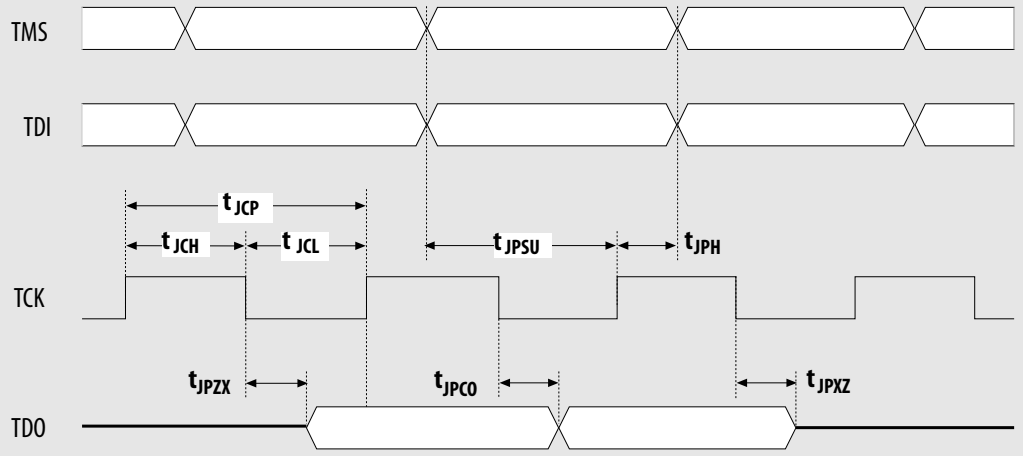
Programmable Output Buffer Delay

Table 1-77: Programmable Output Buffer Delay for Arria V Devices

This table lists the delay chain settings that control the rising and falling edge delays of the output buffer.

You can set the programmable output buffer delay in the Quartus Prime software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

(112) You can set this value in the Quartus Prime software by selecting **D1**, **D3**, **D4**, and **D5** in the **Assignment Name** column of **Assignment Editor**.
(113) Minimum offset does not include the intrinsic delay.

Term	Definition
JTAG timing specifications	JTAG Timing Specifications 

Symbol	Description	V_{CCIO} (V)	Typical	Unit
dR/dV	OCT variation with voltage without re-calibration	3.0	0.0297	%/mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	
dR/dT	OCT variation with temperature without re-calibration	3.0	0.189	%/°C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

Pin Capacitance

Table 2-13: Pin Capacitance for Arria V GZ Devices

Symbol	Description	Maximum	Unit
C_{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C_{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C_{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN\ (DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN\ (AC)}$	AC current per I/O pin	8 mA (124)
$I_{XCVR\text{-}TX\ (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver pin	50 mA

Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ .

Symbol	Description	V_{CCIO} Conditions (V) (125)	Value (126)	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	k Ω
		2.5 ±5%	25	k Ω
		1.8 ±5%	25	k Ω
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	k Ω
		1.25 ±5%	25	k Ω
		1.2 ±5%	25	k Ω

(124) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.
(125) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
(126) These specifications are valid with a ±10% tolerance to cover changes over PVT.

Clock Network	ATX PLL			CMU PLL [161]			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

Standard PCS Data Rate

Table 2-30: Standard PCS Approximate Maximum Date Rate (Gbps) for Arria V GZ Devices

The maximum data rate is also constrained by the transceiver speed grade. Refer to the "Commercial and Industrial Speed Grade Offering for Arria V GZ Devices" table for the transceiver speed grade.

Mode [164]	Transceiver Speed Grade	PMA Width	20	20	16	16	10	10	8	8
		PCS/Core Width	40	20	32	16	20	10	16	8
FIFO	2	C3, I3L core speed grade	9.9	9	7.84	7.2	5.3	4.7	4.24	3.76
	3	C4, I4 core speed grade	8.8	8.2	7.2	6.56	4.8	4.3	3.84	3.44

[161] ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

[164] The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.
(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.
(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.
(195) Requires package skew compensation with PCB trace length.
(196) Do not mix single-ended I/O buffer within LVDS I/O bank.
(197) Chip-to-chip communication only with a maximum load of 5 pF.
(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
4	120	128	ps

Memory Output Clock Jitter Specifications

Table 2-50: Memory Output Clock Jitter Specification for Arria V GZ Devices

The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

Clock Network	Parameter	Symbol	C3, I3L		C4, I4		Unit
			Min	Max	Min	Max	
Regional	Clock period jitter	$t_{JIT(per)}$	–55	55	–55	55	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–110	110	–110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–82.5	82.5	–82.5	82.5	ps
Global	Clock period jitter	$t_{JIT(per)}$	–82.5	82.5	–82.5	82.5	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–165	165	–165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–90	90	–90	90	ps
PHY Clock	Clock period jitter	$t_{JIT(per)}$	–30	30	–35	35	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–60	60	–70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–45	45	–56	56	ps

Note: When you enable the decompression or design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8, FPP ×16, and FPP ×32. For the respective DCLK-to-DATA[] ratio, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.

Table 2-56: FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1

Use these timing parameters when the decompression and design security features are disabled.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1,506 (205)	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 (206)	µs
t_{CF2CK} (207)	nCONFIG high to first rising edge on DCLK	1,506	—	µs
t_{ST2CK} (207)	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_{CD2UM}	CONF_DONE high to user mode (208)	175	437	µs

(205) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(206) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
(207) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.